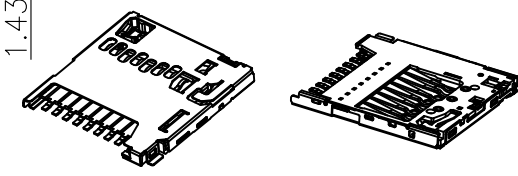
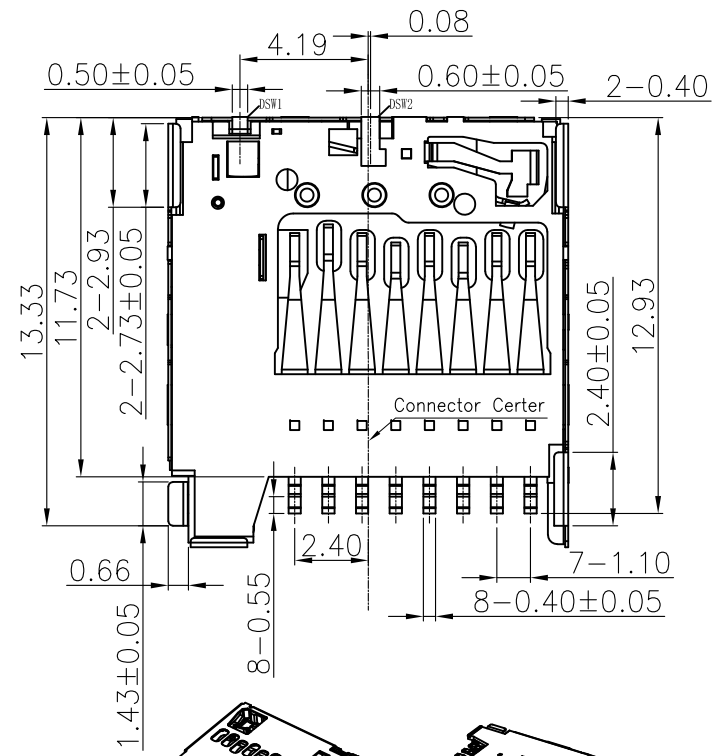
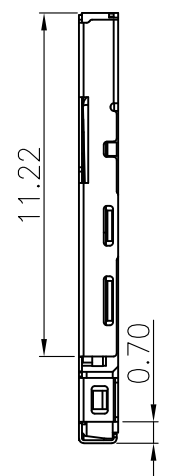
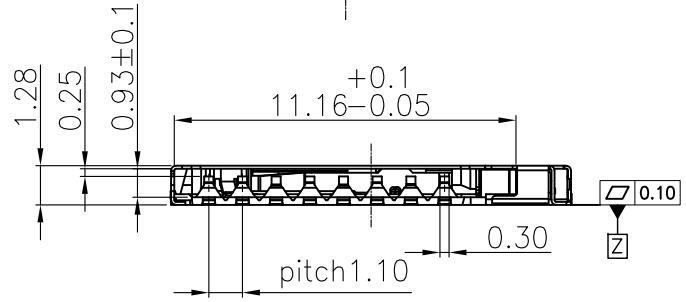
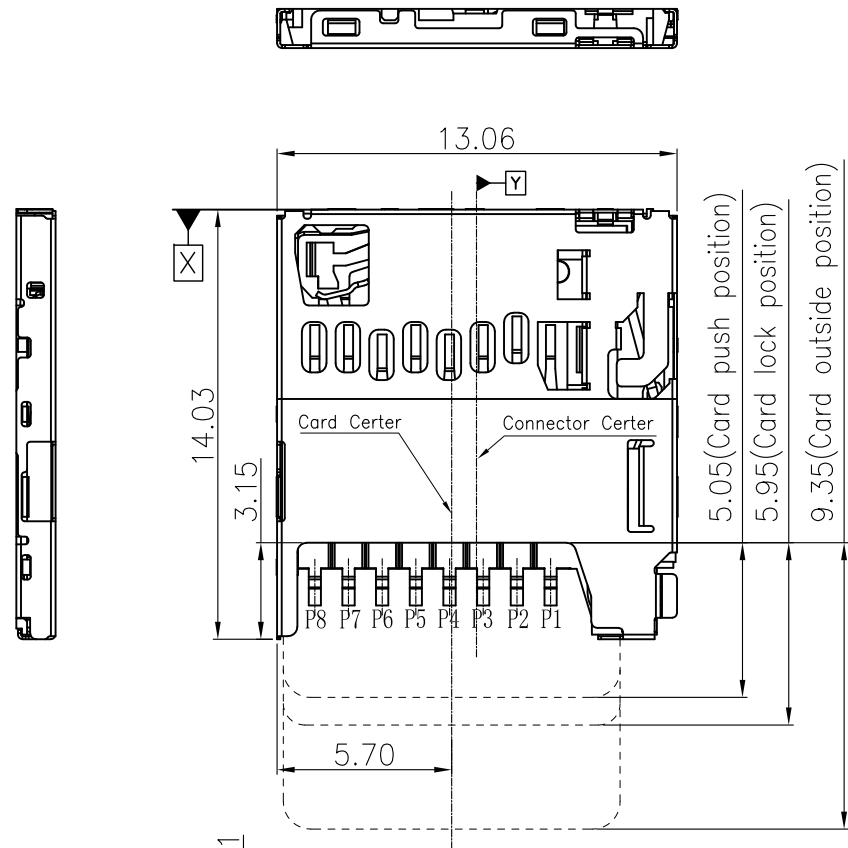


更改 REV	管理内容 MODIFICATION
A	ECXXXXX



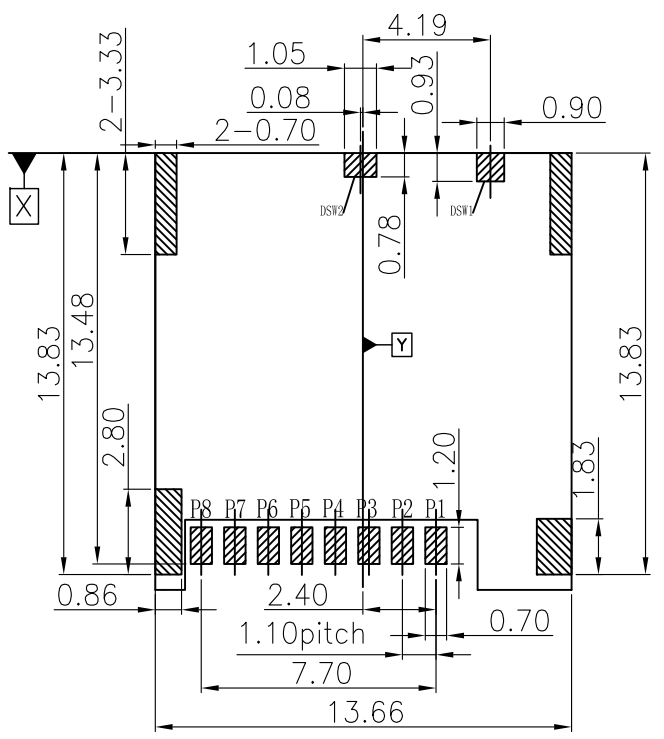
GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X*± 5°	名称/TITLE MICRO SD 1.28H PUSH SMT	
.X± 0.30	.X*± 2°		
.XX± 0.20	.XX*± 1°		
单位(UNIT) mm	料号(PART NO.) 7MSDP-FA-0024	图号(DWG NO.) 7MSDP-FA-0024	比例(SCALE) 1:1
审核(APPROVAL)	核校(CHECKED)	製圖(DRAWN)	张数(SHEET) 1/2
			更改(REV) A



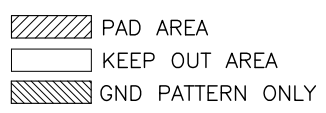
更改 REV	修改 內容
A	ECXXXX

Specification

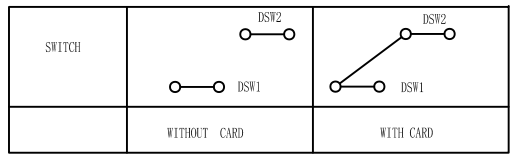
- 1.MATERIAL:
 - 1.1 Insulator:High Temperature Thermoplastic,
LCP black UL94V-0.
 - 1.2 Terminal: Phosphor Bronze.
 - 1.3 Shell: STAINLESS STEEL.
- 2.Plating:
 - 2.1 Terminal: Plated 80u"min Ni Overall
Plated 1u"min Au Selective contact area
Plated 1u"min AU over Ni on solder area
 - 2.2 Shell: Plated 1u"min AU overll 50u"min Ni
- 3.Property:
 - 3.1 Current Rating :0.5A AC/DC max.
 - 3.2 Voltage Rating :12V AC/DC
 - 3.3 Ambient Temperature Range :-20°C~+60°C
 - 3.4 Ambient Humidity Range :95% R.H. Max.
 - 3.5 Contact Resistance:100mΩ max.
 - 3.6 Insulation Resistance:1000MΩ min./500VDC
 - 3.7 Durability:5000 cycles



RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)



PIN NO.	PIN ASSIGNMENT
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
P7	DAT0
P8	DAT1



GENERAL TOLERANCE		KINGCONN 皇海科技股份有限公司	
X± 0.50	X.*± 5 °	名稱(TITLE) MICRO SD 1.28H PUSH SMT	
.X± 0.30	.X.*± 2 °		
.XX± 0.20	.XX.*± 1 °		
單位(UNIT) mm	料號(PART NO.) 7MSDP-FA-0024	圖號(DWG NO.) 7MSDP-FA-0024	
審核(APPROVAL)	核對(CHECKED)	製圖(DRAWN)	比例 SCALE 1:1
			張數 SHEET 2/2
			更改 REV A